General Description

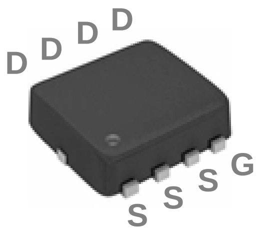
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

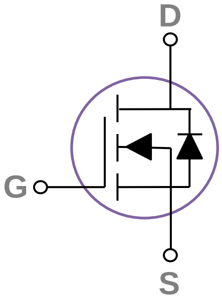
BVDSS	RDSON	ID
40V	6.8mΩ	60A

Features

- *40V, 60A, RDS(ON) =6.8mΩ@VGS = 10V*
- *Improved dv/dt capability*
- *Fast switching*
- *Green Device Available*

PPAK3X3 Pin Configuration





Applications

- *MB / VGA / Vcore*
- *POL Applications*
- *SMPS 2nd SR*

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current – Continuous (T_C=25℃)	60	A
	Drain Current – Continuous (T_C=100℃)	38	A
I_D	Drain Current – Continuous (T_A=25℃)	13	A
	Drain Current – Continuous (T_A=70℃)	10.5	A
I_{DM}	Drain Current – Pulsed[1]	240	A
EAS	Single Pulse Avalanche Energy[2]	76	mJ
IAS	Single Pulse Avalanche Current[2]	39	A
P_D	Power Dissipation (T_C=25℃)	51	W
	Power Dissipation – Derate above 25℃	0.41	W/℃
P_D	Power Dissipation (T_A=25℃)	2	W
	Power Dissipation – Derate above 25℃	0.02	W/℃
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.44	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250μA	40	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.03	---	V/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=40V , V_{GS}=0V , T_J=25℃	---	---	1	μA
		V_{DS}=32V , V_{GS}=0V , T_J=125℃	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance[3]	V_{GS}=10V , I_D=10A	---	5.7	6.8	mΩ
		V_{GS}=4.5V , I_D=5A	---	7	9	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250μA	1.2	1.6	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5	---	mV/℃
gfs	Forward Transconductance	V_{DS}=10V , I_D=3A	---	12	---	S

Dynamic Characteristics

Q_g	Total Gate Charge[3,4]	V_{DS}=20V , V_{GS}=10V , I_D=30A	---	32	48	nC
Q_{gs}	Gate-Source Charge[3,4]		---	4	6	
Q_{gd}	Gate-Drain Charge[3,4]		---	10	15	
$T_{d(on)}$	Turn-On Delay Time[3,4]	V_{DD}=20V , V_{GS}=10V , R_G=6Ω I_D=30A	---	13.6	20.4	ns
T_r	Rise Time[3,4]		---	2.5	3.8	
$T_{d(off)}$	Turn-Off Delay Time[3,4]		---	68	102	
T_f	Fall Time[3,4]		---	5	7.5	
C_{iss}	Input Capacitance	V_{DS}=20V , V_{GS}=0V , F=1MHz	---	1780	2670	pF
C_{oss}	Output Capacitance		---	185	275	
C_{rss}	Reverse Transfer Capacitance		---	150	220	
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	1.4	---	Ω

Drain-Source Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	60	A
I_{SM}	Pulsed Source Current[3]		---	---	120	A
V_{SD}	Diode Forward Voltage[3]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V
t_{rr}	Reverse Recovery Time	V_R=30V, I_S=10A , di/dt=100A/µs, T_J=25℃	---	40	---	ns
Q_{rr}	Reverse Recovery Charge		---	20	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=39A., Starting T_J=25℃
3. The data tested by pulsed , pulse width ≦ 300µs , duty cycle ≦ 2%.
4. Essentially independent of operating temperature.

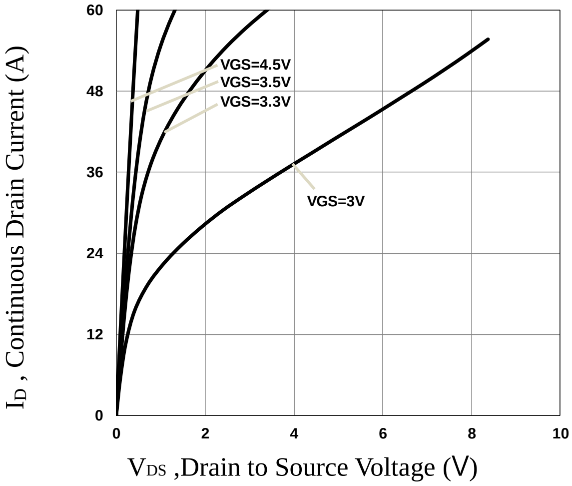


Fig.1 Typical Output Characteristics

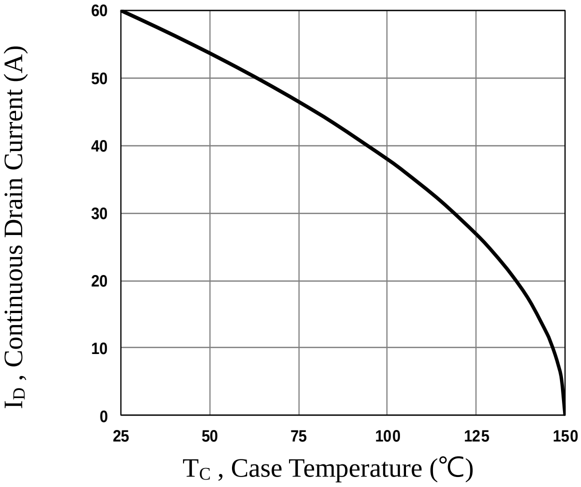


Fig.2 Continuous Drain Current vs. T_C

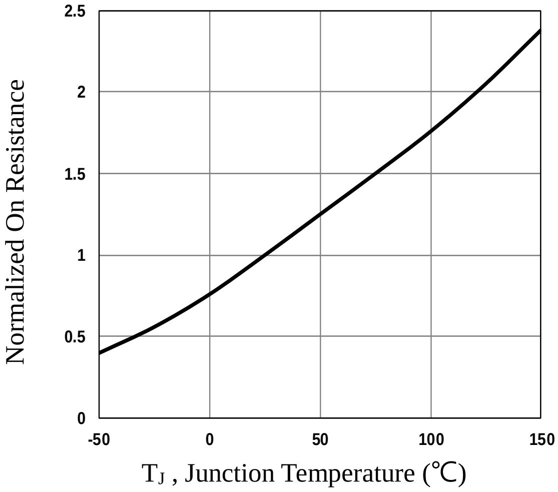


Fig.3 Normalized RDSON vs. T_J

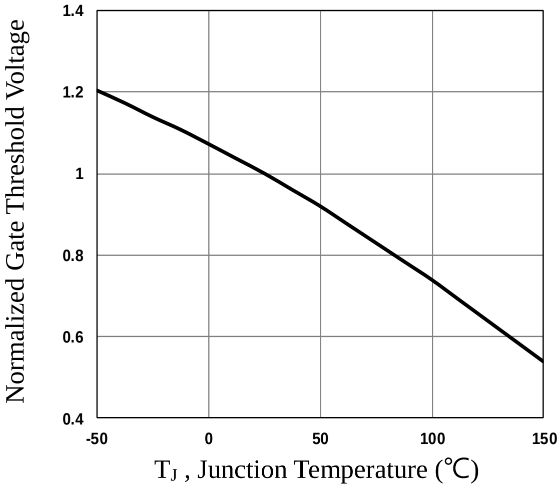


Fig.4 Normalized V_{th} vs. T_J

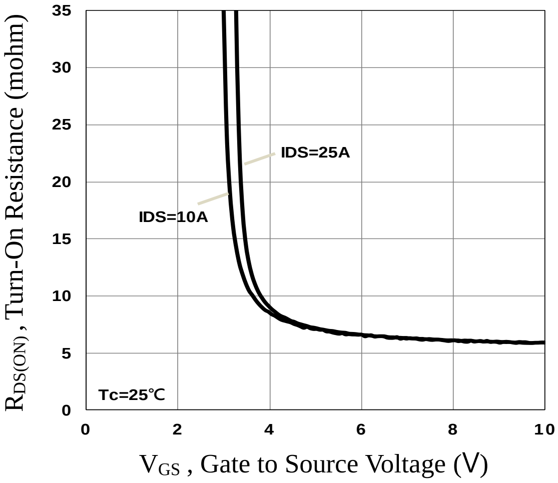


Fig.5 Turn-On Resistance vs. V_{GS}

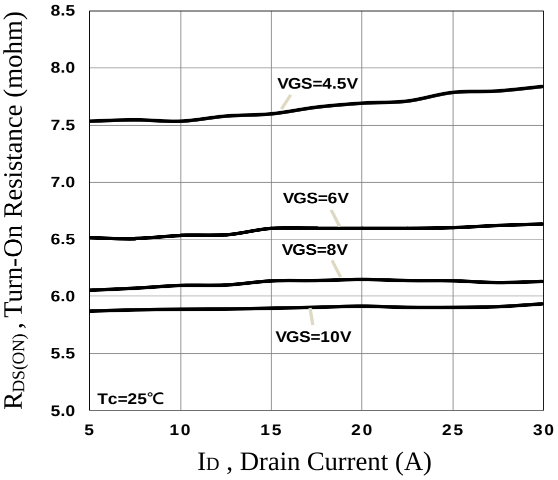


Fig.6 Turn-On Resistance vs. I_D

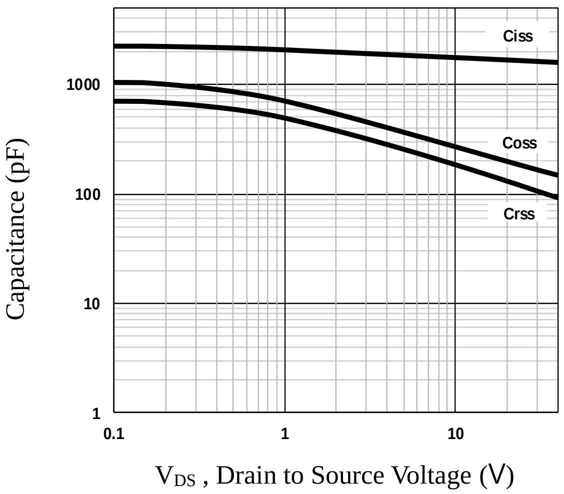


Fig.7 Capacitance Characteristics

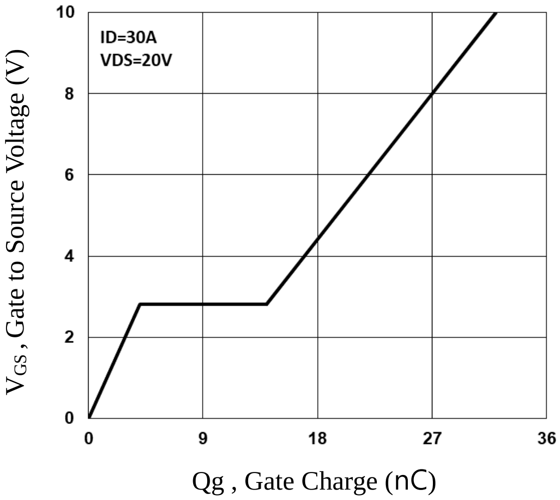


Fig.8 Gate Charge Characteristics

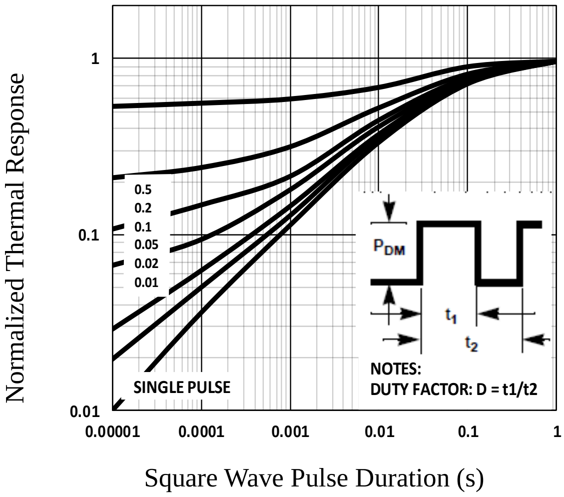


Fig.9 Normalized Transient Impedance

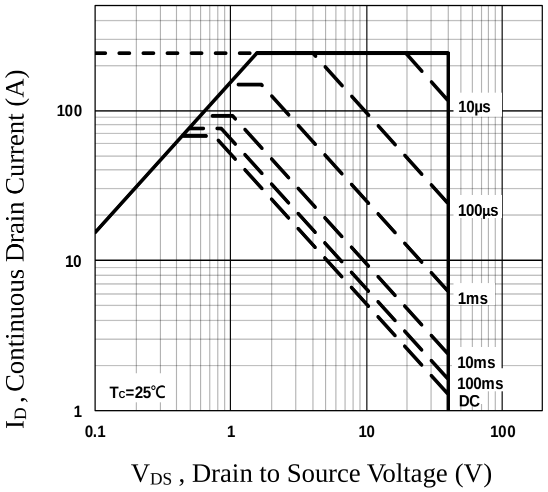


Fig.10 Maximum Safe Operation Area

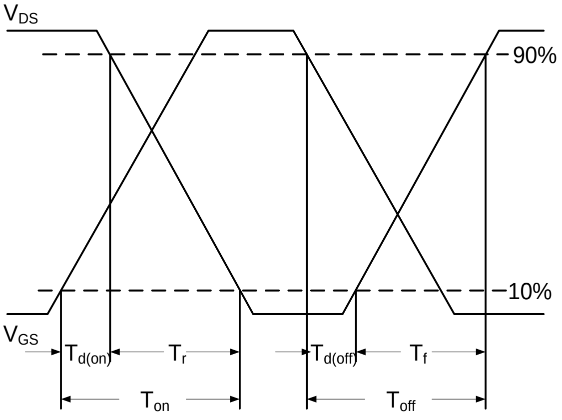


Fig.11 Switching Time Waveform

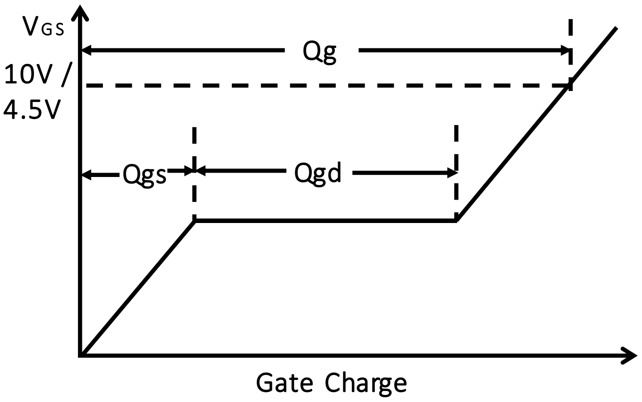
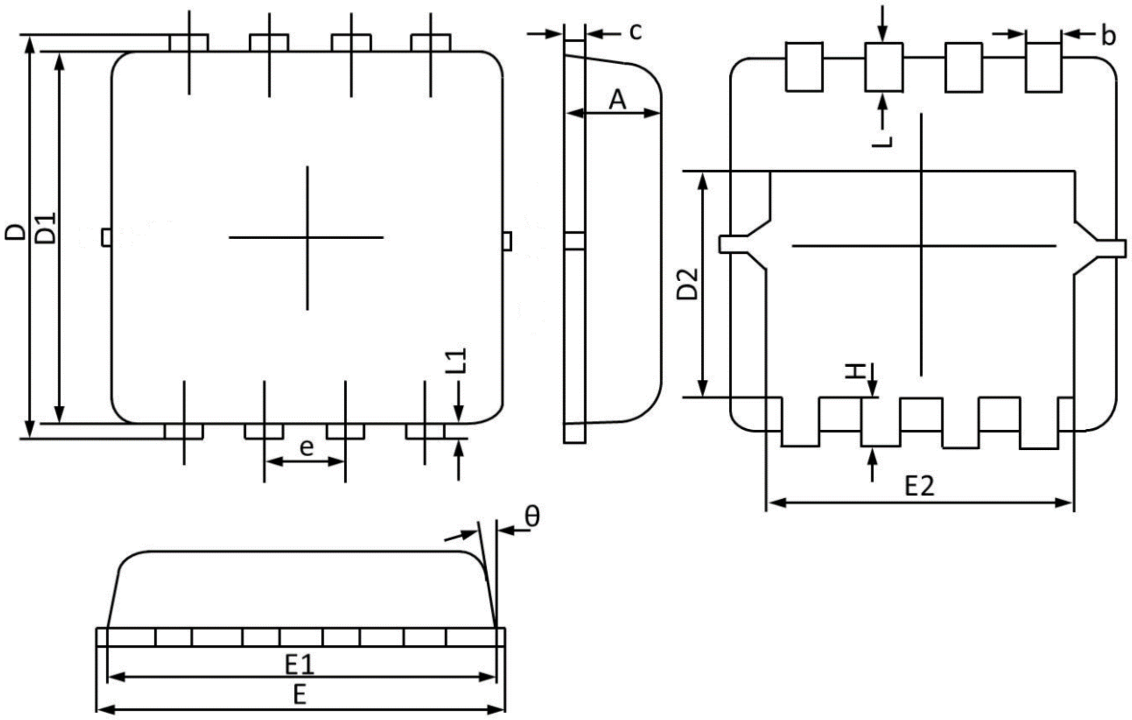


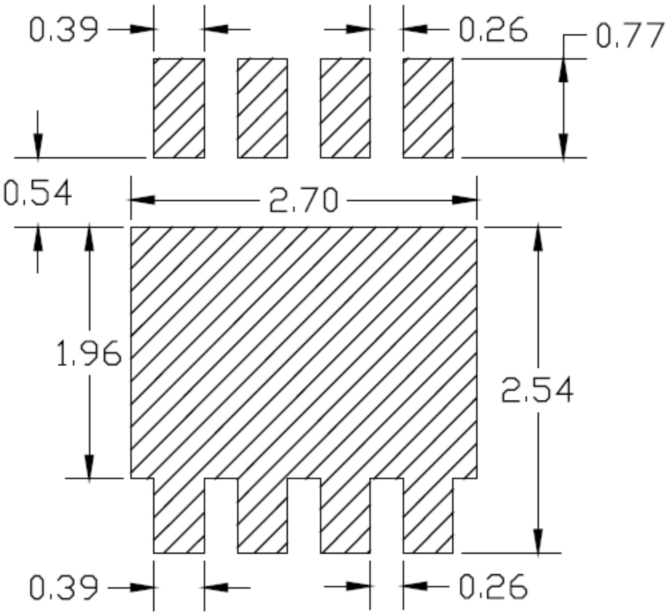
Fig.12 Gate Charge Waveform

PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.250	0.014	0.010
c	0.250	0.100	0.010	0.004
D	3.500	3.050	0.138	0.120
D1	3.200	2.900	0.126	0.114
D2	1.950	1.350	0.077	0.053
E	3.400	3.000	0.134	0.118
E1	3.300	2.900	0.130	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.750	0.300	0.030	0.012
L	0.600	0.300	0.024	0.012
L1	0.200	0.060	0.008	0.002
θ	14°	6°	14°	6°

PPAK3X3 RECOMMENDED LAND PATTERN



unit : mm